

ABSTRACT OF THE DISCLOSURE

The resist application method comprises the steps of: thermal processing for evaporating water from the surface of a wafer 10; making the surface of the wafer 10 hydrophobic with a hydrophobic processing material; and applying a resist onto the wafer 10, and the step of thermal processing to the step of making the surface of the wafer 10 hydrophobic are performed in a dehumidified atmosphere.